

# **Product Change Notice (PCN)**

Subject: Design and Mold Compound Change for the Intersil ISL78600ANZ\* Products

Publication Date: 4/20/2016 Effective Date: 7/20/2016

#### **Revision Description:**

Initial Release

#### **Description of Change:**

All level and mold compound change to the ISL78600ANZ\* to improve overall product performance.

Part numbers affected - ISL78600ANZ; ISL78600ANZ-T

#### Reason for Change:

The changes include several product performance improvements as listed below:

- 1. BGREF implemented an amended secondary reference to improve performance post assembly of device onto printed circuit board.
- 2. Improved Latch-up performance

The mold compound change improves thermal stability of device post solder, for better precision performance.

The changes align the datasheet with the product characteristics and is necessary to maintain product manufacturability in support of customer delivery requirements. Details regarding the changes are contained in Appendix B. the updated data sheet is available on the Intersil web site at:

http://www.intersil.com/content/dam/Intersil/documents/isl7/isl78600.pdf

### Impact on fit, form, function, quality & reliability:

The change will have no other impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

#### **Product Identification:**

Product affected by this change is identifiable via Intersil's internal traceability system.

Qualification status: Complete, see Appendix A

Sample availability: 4/20/2016

Device material declaration: Available upon request

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.

For additional information regarding this notice, please contact your regional change coordinator (below)							
Americas: PCN-US@INTERSIL.COM	Europe: PCN-EU@INTERSIL.COM	Japan: PCN-JP@INTERSIL.COM	Asia Pac: PCN-APAC@INTERSIL.COM				



Appendix A: Qualification Results

Qualification Results						
Stress	Test Method	Sample Size (total)	# of Lots	Result		
High Temperature Operating Life (HTOL)	JESD22-A108	231	3	Pass		
Early Life Failure Rate (ELFR)	AEC Q100-008	2400	3	Pass		
Biased Hast (BHAST)	JESD22-A110	231	3	Pass		
High Temperature Storage (HTS)	JESD22-A103	45	1	Pass		
Unbiased HAST (UHAST)	JESD22-A118	231	3	Pass		
Temperature Cycle (TC)	JESD22-A104	231	3	Pass		



## Appendix B: Datasheet Electrical Table Changes

#### From:

#### **Absolute Maximum Ratings**

Unless otherwise specified, With respect to VSS.

			COMMS F		10000
				0.2V to	
V2P5			 	0.2V to	2.9
VBAT			 	0.5V t	0 63
Dhi1, DLo1, [	DHi2, DI	Lo2 .	 	0.5V to (VBAT +	0.5
vco			 	0.5V to	+9.0
VC1			 	0.5V to	+18
				0.5V to	
				0.5V to	
				0.5V to	
				0.5V to	
				0.5V to	
				0.5V to	
				0.5V to	
				0.5V to	
				0.5V to	
				0.5V to	
				0.5V to	
				0.5 to VBAT	
				0.5 to VBAT	
				V(VCn-1) -0.5V to V(VCn-	

ESD Rating

Human Body Model (Tested per JESD22-A114F). 2kV

Capacitive Discharge Model (Tested per JESD22-C101D). 500V

Latch-up (Tested per JESD-78B; Class 2, Level A). 100mA

NOTE: DOUT, DATA READY, and FAULT are digital outputs and should not be driven from external sources. V2P5, REF, TEMPREG and BASE are analog outputs and should not be driven from external sources.

#### Thermal Information

Thermal Resistance (Typical)	OJA(C/W)	OJC(C/W)
64 Ld TQFP Package (Notes 5, 6)	49	9
Max Continuous Package Power Dissipation .		400mW
Storage Temperature	5	5°C to +125°C
Max Operating Junction Temperature		+125°C
Ph-Free Reflow Profile	Refer to JED	EC LSTD 020D

#### **Recommended Operating Conditions**

TA, Ambient Temperature Range	40°C to +105°C
V <sub>BAT</sub>	6V to 60V
V <sub>BAT</sub> (Daisy Chain Operation)	10V to 60V
VCn (for n = 1 to 12)	V(VCn-1) to V(VCn-1) + 5V
VCO	0.1V to 0.1V
CBn (for n = 1 to 9)	V(VCn-1) to V(VCn-1) + 9V
CBn (for n = 10 to 12)	V(VCn) -9V to V(VCn)
DIN, SCLK, CS, COMMS SELECT 1, COMMS SI	ELECT 2, V3P3, VCC,
COMMS RATE O, COMMS RATE 1, EN	
ExT1, ExT2, ExT3, ExT4	

#### To:

## Absolute Maximum Ratings Unless otherwise

specified. With respect to VSS

BASE
DIN, SCLK, CS, DOUT, DATA READY, COMMS SELECT n, ExTn,
TEMPREG, REF, V3P3, VCC, FAULT, COMMS RATE n,
EN, VDDEXT0.2V to 4.1V
V2P50.2V to 2.9V
VBAT0.5V to 63V
Dhi1, DLo1, DHi2, DLo20.5V to (VBAT + 0.5V)
VC00.5V to +9.0V
VC10.5V to +18V
VC20.5V to +18V
VC30.5V to +27V
VC4
VC50.5V to +36V
VC60.5V to +36V
VC70.5V to +45V
VC80.5V to +45V
VC90.5V to +54V
VC100.5V to +63V
VC110.5V to +63V
VC120.5V to +63V
VCn (for n = 0 to 12)
CBn (for n = 1 to 12)
CBn (for n = 1 to 9)
CBn (for n = 10 to 12) V(VCn) -9V to V(VCn) +0.5V
Current into VCn, VBAT, VSS (Latch-Up Test)

Current into VCn, VBAT, VSS (Latch-Up Test)	±100m/
ESD Rating	
Human Body Model (Tested per AECQ100-002)	2k
Capacitive Discharge Model (Tested per AECQ100-011)	2k
Latch-Up (Tested per AEC-Q100-004; Class 2, Level A)	. 100m/
NOTE: DOUT, DATA READY, and FAULT are digital outputs and sh	ould not
be driven from external sources. V2P5, REF, TEMPREG and BASE	are
analog outputs and should not be driven from external sources.	

#### Thermal Information

Thermal Resistance (Typical)	θ <sub>IA</sub> (C/W)	θ <sub>IC</sub> (C/W)
64 Ld TQFP Package (Notes 6, 7)	42	9
Maximum Continuous Package Power Dissipa	ation	400mW
Storage Temperature	55	5°C to +125°C
Maximum Operating Junction Temperature		+125°C
Pb-Free Reflow Profile		see TB493

#### **Recommended Operating Conditions**

IA, Ambient Temperature Range	40 C to +105 C
V <sub>BAT</sub>	6V to 60V
VBAT (Daisy Chain Operation)	10V to 60V
VCn (for n = 1 to 12)	.V(VCn-1) to V(VCn-1) + 5V
vco	0.1V to 0.1V
CBn (for n = 1 to 9)	.V(VCn-1) to V(VCn-1) + 9V
CBn (for n = 10 to 12)	
DIN, SCLK, CS, COMMS SELECT 1, COMMS SELEC	CT 2, V3P3, VCC,
COMMS RATE 0, COMMS RATE 1, EN	
ExT1, ExT2, ExT3, ExT4	

### From:

Electrical Specifications V<sub>BAT</sub> = 6 to 60V, T<sub>A</sub> = -20°C to +60°C, unless otherwise specified. Biasing setup as in

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 7)	TYP	MAX (Note 7)	UNITS
Power-Up Condition Threshold	V <sub>POR</sub>	V <sub>BAT</sub> voltage (rising)	4.8	5.1	5.6	V
Power-Up Condition Hysteresis	V <sub>PORhys</sub>			400		mV

Power-Up Condition Threshold	V <sub>POR</sub>	V <sub>BAT</sub> voltage (rising)	4.8	5.1	5.6	V
Power-Up Condition Hysteresis	V <sub>PORhys</sub>			460		mV



PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 7)	TYP	MAX (Note 7)	UNITS		
BAT Supply Current	IVBAT	Non Datsy Chain configuration. Device enabled. No communications, ADC, measurement, balancing or open wire detection activity.						
		6V	7	35	80	μA		
		39.6V	0	64	241	μA		
		60V	0	90	250	μА		
		-40°C to +105°C (Note 9)	0		280	μА		
	IVBATMASTER	Dalsy Chain configuration – master device. Enabled. N balancing or open wire detection activity.	o communica	tions, AD	C, measure	ment,		
		ov	400	530	660	μA		
		39.6V	500	680	900	μA		
		cov	550	750	1000	μA		
001		-40°C to +105°C (Note 9)		\	1150	μA		
		Peak current when Dalsy Chain transmitting		18		mA		
	VBATMID	Dalsy Chain configuration - MIDDLE stack device. Ena measurement, balancing or open wire detection activity		municatio	ons, ADC,			
		ov	700	1020	1210	μА		
		39.6V	900	1250	1560	μА		
		60V	1000	1400	1700	μА		
		-40°C to +105°C (Note 9)			1850	μА		
		Peak current when Dalsy Chain transmitting		18		mA		
	IVBATTOP	Daisy Chain configuration - top device. Enabled. No communications, ADC, measurement, balancing or open wire detection activity.						
		6V	400	530	660	μA		
		39.6V	500	680	900	μА		
		GOV	550	750	1000	μА		
		-40°C to +105°C (Note 9)			1150	μА		
		Peak Current when Dalsy Chain transmitting		18		mA		
	VBATSLEEP1	1 Sleep mode (EN = 1, Daisy Chain configuration)						
	(Note 9)	6V	14	18	23	μА		
		39.6V	18	23	29	μА		
		GOV	20	25	30	μА		
		-40°C to +105°C			41	μА		
	IVBATSLEEP2	Sieep mode (EN = 1, Stand-alone, non-Dalsy Chain)	3.5	8	16	μА		
	(Note 9)	-40°C to +105°C	3		70	μA		
	VBATSHON	Shutdown, device "off" (EN = 0) (Dalsy Chain and Non-	Dalsy Chain o	onfigurati	ions)			
	(Note 9)	ov	1.5	7	15.5	μА		
		39.6V	3	7	18	μА		
		GOV	5	7	23	μА		
	1			_	_	-		

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 8)	TYP	MAX (Note 8)	UNIT	
Supply Current Specifications		1	-			_	
V <sub>BAT</sub> Supply Current	IVBAT	Non-daisy chain configuration. Device enabled. No co balancing or open-wire detection activity.	mmunication	s, ADC, m	neasurement		
		6V		70	90	μА	
		39.6V		73	95	μА	
		60V		73	96	μА	
		-40 °C to +105 °C (Note 9)			105	μА	
	VBATMASTER	Daisy chain configuration – master device, Enabled, I balancing or open-wire detection activity.	lo communic	ations, Al	DC, measure	ment,	
		σv	400	550	660	μА	
		39.6V	500	650	900	μА	
		60V	550	710	1000	μА	
		-40 °C to +105 °C (Note 9)			1150	μ	
		Peak current when daisy chain transmitting		18		m	
	IVBATMID	Daisy chain configuration - Middle stack device. Enal measurement, balancing or open-wire detection activ		nunicatio	ins, ADC,		
		6V	700	1020	1210	μ/	
		39.6V	900	1210	1560	μA	
		60V	1000	1340	1700	μ/	
		-40 °C to +105 °C (Note 9)			1850	μ	
		Peak current when daisy chain transmitting		18		m	
	IVBATTOP	Dep Dalsy chain configuration – top device, Enabled, No communications, ADC, measurement, balancing or open-wire detection activity.					
		6V	400	550	660	μ/	
		39.6V	500	650	900	μ	
		60V	550	710	1000	μ/	
		-40 °C to +105 °C (Note 9)			1150	μ	
		Peak current when daisy chain transmitting		18		m	
	VBATSLEEP1	Sleep mode (EN = 1, daisy chain configuration)					
	(Note 9)	ov	13	28	44	μ	
		39.6V	18	33	48	μ	
		60V	20	35	50	μ/	
		-40 °C to +105 °C			120	μέ	
	VBATSLEEP2	Sleep mode (EN = 1, stand-alone, non-dalsy chain)	13.2	19	34.1	μ/	
	(Note 9)	-40°C to +105°C	13.5		109	μ/	
	VBATSHDN	Shutdown. device "off" (EN = 0) (Dalsy chain and nor	n-dalsy chain	configur	ations)		
	(Note 9)	ov	6	13	28	μέ	
		39.6V	7	15	29	μА	
		60V	7	16	30	ш	
	1	-40°C to +105°C			101	μА	



PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 7)	ТҮР	MAX (Note 7)	UNITS
VBAT Supply Current Tracking, Sleep Mode.	(Note 9)	EN = 1, Daisy Chain Sleep Mode configuration. VBAT current difference between any two devices operating at the same temperature and supply voltage.	0	4	8	μА
		-40°C to +105°C	0		17	μА

# To:

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 8)	TYP	MAX (Note 8)	UNIT
V <sub>BAT</sub> Supply Current Tracking. Sleep Mode.	(Note 9)	EN = 1, daisy chain sleep mode configuration. V <sub>BAT</sub> current difference between any two devices operating at the same temperature and supply voltage.	0		18	μΑ
		-40°C to +105°C	0		56	μА

### From:

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 7)	TYP	MAX (Note 7)	UNITS
VBAT Incremental Supply Current, Balancing	VBATBAL	All balancing circuits on. Incremental current: Add to nonbalancing V <sub>BAT</sub> current. V <sub>BAT</sub> = 39.6V	250	300	350	μА
		-40°C to +105°C (Note 9)	200	300	400	μА
V3P3 Regulator Voltage (Normal)	V <sub>3P3N</sub>	EN = 1, Load current range 0 to 5mA. VBAT = 39.6V	3.25	3.35	3.45	v
		-40°C to +105°C (Note 9)	3.2		3.5	v
V3P3 Regulator Voltage (Sleep)	V <sub>3P3S</sub>	EN = 1, Load current range. No load. (SLEEP). V <sub>BAT</sub> = 39.6V	2.45	2.7	2.95	v
		-40°C to +105°C (Note 9)	2.4		3.05	v
V3P3 Regulator Control Current	BASE	Current sourced from BASE output. VBAT = 6V	1	1.5		mA
		-40°C to +105°C (Note 9)	1			mA
V3P3 Supply Current	lv3P3	Device Enabled No measurement activity, Normal Mode	0.8	1	1.2	mA
		-40°C to +105°C (Note 9)	0.8		1.3	mA
V <sub>REF</sub> Reference Voltage	V <sub>REF</sub>	EN = 1, No Load, Normal Mode		2.5		V
VDDEXT Switch Resistance	RVDDEXT	Switch "On" resistance, VBAT = 39.6V	8	12	17	Ω
		-40°C to +105°C (Note 9)	5		22	Ω
VCC Supply Current	lvec	Device enabled (EN = 1). Stand-Alone or Dalsy Configuration. No ADC or Dalsy Chain communications active.	2.0	3.25	4.5	mA
		-40°C to +105°C (Note 9)	2.0		5.0	mA
	VCCACTIVE1	Device enabled (EN = 1). Stand-Alone or Dalsy Confliguration. Average current during 16ms Scan Continuous operation. V <sub>BAT</sub> = 39.6V		6.0		mA
	VCCSLEEP	Device enabled (EN = 1). Sleep mode. VBAT = 39.6V		2.4		μА
	VCCSHDN	Device disabled (EN = 0). Shutdown mode.	0	1.2	4.1	μА
		-40°C to +105°C (Note 9)			9.0	μА

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 8)	TYP	MAX (Note 8)	UNIT
V <sub>BAT</sub> incremental Supply Current, Balancing	VBATBAL	All balancing circuits on. Incremental current: Add to non-balancing V <sub>BAT</sub> current. V <sub>BAT</sub> = 39.6V	250	300	350	μА
		-40 °C to +105 °C (Note 9)	200	300	400	μА
V3P3 Regulator Voltage (Normal)	V <sub>3P3N</sub>	EN = 1, Load current range 0 to 5mA. V <sub>BAT</sub> = 39.6V	3.25	3.35	3.45	V
		-40 °C to +105 °C (Note 9)	3.2		3.5	v
V3P3 Regulator Voltage (Sleep)	V <sub>3P3S</sub>	EN = 1, Load current range. No load. (SLEEP). V <sub>BAT</sub> = 39.6V		2.8		v
V3P3 Regulator Control Current	IBASE	Current sourced from BASE output. V <sub>BAT</sub> = 6V	1			mA
		-40 °C to +105 °C (Note 9)	1			mA
V3P3 Supply Current	I <sub>V3P3</sub>	Device enabled No measurement activity, Normal mode	0.8	1	1.2	mA
		-40 °C to +105 °C (Note 9)	0.8		1.3	mA
V <sub>REF</sub> Reference Voltage	V <sub>REF</sub>	EN = 1, no load, normal mode		2.5		V
VDDEXT Switch Resistance	RVDDEXT	Switch "ON" resistance, VBAT = 39.6V		12		Ω
		-40 °C to +105 °C (Note 9)	5		22	Ω
VCC Supply Current	lvoc	Device enabled (EN = 1). Stand-alone or datsy configuration. No ADC or datsy chain communications active.	2.00	3.25	4.50	mA
		-40 °C to +105 °C (Note 9)	2.0		5.0	mA
	VCCACTIVE1	Device enabled (EN = 1). Stand-alone or dalay configuration, average current during 16ms scan continuous operation. V <sub>BAT</sub> = 39.6V		6.0		mA
	VCCSLEEP	Device enabled (EN = 1). Sleep mode. V <sub>BAT</sub> = 39.6V		0.5		μА
	VCCSHDN	Device disabled (EN = 0). Shutdown mode.	0	0.5	3.5	μА
		-40 °C to +105 °C (Note 9)			9.0	μА



PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 7)	TYP	MAX (Note 7)	UNITS			
Cell Input Current.	IVCELL	VCO Input							
Note: Cell accuracy figures assume a fixed		VCO ≥ 0.5 and VCO ≤ 4.0V	-1.5	-1	-0.5	μA			
1kΩ resistor is placed in series with each		VCO > 4.0V	-1.75		-0.5	μA			
VCn pin (n = 0 to 12)		-40°C to +105°C (Note 9)	-2.0	-1	-0.5	μА			
		VC1, VC2, VC3 Inputs							
		VCn - VC(n-1) ≥ 0.5 and VCn-VC(n-1) ≤ 4.0V	-2.7	-2	-1.3	μA			
		VCn - VC(n-1) > 4.0V	-2.85		-1.0	μA			
		-40°C to +105°C (Note 9)	-3.0	-2	-0.84	μА			
		VC4 Input							
		VCn - VC(n-1) ≥ 0.5 and VCn-VC(n-1) ≤ 4.0V	-0.6	0	0.71	μА			
		VCn - VC(n-1) > 4.0V	-0.8		1.15	μА			
		-40°C to +105°C (Note 9)	-0.84	0	1.31	μА			
		VC5, VC6, VC7, VC8, VC9, VC10, VC11 Inputs							
		VCn - VC(n-1) < 2.6V	0.5	2	2.7	μА			
		VCn - VC(n-1) ≥ 2.6V and VCn-VC(n-1) ≤ 4.0V	1.32	2	2.89	μА			
		VCn - VC(n-1) > 4.0V	1.16	2	3.33	μА			
		-40°C to +105°C (Note 9)	0.5	2	3.43	μА			
		VC12 Input	1						
		VC12 - VC11 ≥ 0.5 and VC12-VC11 ≤ 4.0V	0.37	1	1.85	μА			
		VC12 - VC11 > 4.0V	0.19		2.3	μА			
		-40°C to +105°C (Note 9)	0.15	1	2.47	μА			

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 8)	TYP	MAX (Note 8)	UNIT				
Cell Input Current.	Ivcell	VCO Input								
Note: Cell accuracy figures assume a		VC0 ≥ 0.5 and VC0 ≤ 4.0V	-1.5	-1	-0.5	μА				
fixed 1kΩ resistor is placed in series with		VCO > 4.0V	-1.75		-0.50	μА				
each VCn pin (n = 0 to 12)		-40°C to +105°C (Note 9)	-2.0	-1	-0.5	μА				
		VC1, VC2, VC3 Inputs								
		VCn - VC(n-1) ≥ 0.5 and VCn-VC(n-1) ≤ 4.0V	-2.7	-2	-1.3	μА				
		VCn - VC(n-1) > 4.0V	-2.85		-1.00	μА				
		-40°C to +105°C (Note 9)	-3.0	-2	-1.0	μА				
		VC4 Input	24 Input							
		VCn - VC(n-1) ≥ 0.5 and VCn-VC(n-1) ≤ 4.0V	-0.6	0	0.6	μА				
		VCn - VC(n-1) > 4.0V	-0.7		0.7	μА				
		-40°C to +105°C (Note 9)	- 0.8	0	0.8	μА				
		VC5, VC6, VC7, VC8, VC9, VC10, VC11 Inputs								
		VCn - VC(n-1) < 2.6V	0.5	2	2.7	μА				
		VCn - VC(n-1) ≥ 2.6V and VCn-VC(n-1) ≤ 4.0V	1.5	2	2.7	μА				
		VCn - VC(n-1) > 4.0V	1.50	2	2.85	μА				
		-40°C to +105°C (Note 9)	0.5	2	3.0	μА				
		VC12 Input	•							
		VC12 - VC11 ≥ 0.5 and VC12 - C11 ≤ 4.0V	0.6	1	1.7	μА				
		VC12 - VC11 > 4.0V	0.60		1.75	μА				
		-40°C to +105°C (Note 9)	0.6	1	2.0	μА				



PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 7)	TYP	MAX (Note 7)	UNITS
Initial V <sub>BAT</sub> monitor Voltage Error	ΔV <sub>BAT</sub>	Measured at V <sub>BAT</sub> = 36V to 43.2V	-100		100	mV
(Note 10)		Measured at V <sub>BAT</sub> = 31.2V to 48V	-125		125	mV
		Measured at VBAT = 31.2V to 59.4V	-250		250	mV
		Measured at V <sub>BAT</sub> = 6V to 59.4V	-320		332	mV
		Measured at V <sub>BAT</sub> = 6V to 59.4V -40 °C to +105 °C ( <u>Note 9</u> )	-490		490	mV
External Temperature Monitoring Regulator	V <sub>TEMP</sub>	Voltage on TEMPREG output. (0 to 2mA load)	2.475	2.5	2.525	V
External Temperature Output Impedance	R <sub>TEMP</sub>	Output Impedance at TEMPREG pin. (Note 9)	0	0.1	0.2	Ω
External Temperature Input Range	V <sub>EXT</sub>	Effective EXTn input voltage range. For design reference. This is the input voltage range that does not trigger an open input condition.	0		2344	mV
External Temperature Input Pull-up	R <sub>EXTTEMP</sub>	Pull-up resistor to V <sub>TEMPREG</sub> applied to each input during measurement		10		МΩ
External Temperature Input Offset	V <sub>EXTOFF</sub>	V <sub>BAT</sub> = 39.6V	-7.0		7.0	mV
		V <sub>BAT</sub> = 39.6V, -40°C to +105°C ( <u>Note 9</u> )	-10		10	m۷
External Temperature Input INL	V <sub>EXTINL</sub>	(Note 9)	-0.65		0.65	mV
External Temperature Input Gain Error	V <sub>EXTG</sub>	Error at 2.5V input	-7.5		11	mV
		-40°C to +105°C (Note 9)	-13.4		19.3	m۷

#### To:

# Measured @ $V_{BAT}$ = 31.2v to 59.4V removed from datasheet

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 8)	TYP	MAX (Note 8)	UNIT
Initial V <sub>BAT</sub> monitor Voltage Error	ΔV <sub>BAT</sub>	Measured at V <sub>BAT</sub> = 36V to 43.2V	-100		100	mV
(Note 10)		Measured at V <sub>BAT</sub> = 31.2V to 48V	-125		125	mV
		Measured at V <sub>BAT</sub> = 6V to 59.4V	-320		322	mV
		Measured at V <sub>BAT</sub> = 6V to 59.4V -40 °C to +105 °C ( <u>Note 9</u> )	-490		490	mV
External Temperature Monitoring Regulator	V <sub>TEMP</sub>	Voltage on TEMPREG output. (O to 2mA load)	2.475	2.500	2.525	V
External Temperature Output Impedance	R <sub>TEMP</sub>	Output Impedance at TEMPREG pin. (Note 9)	0	0.1	0.2	Ω
External Temperature Input Range	V <sub>EXT</sub>	Effective ExTn input voltage range. For design reference. This is the input voltage range that does not trigger an open input condition.	0		2344	mV
External Temperature Input Pull-Up	R <sub>EXTTEMP</sub>	Pull-up resistor to V <sub>TEMPREG</sub> applied to each input during measurement		10		MΩ
External Temperature Input Offset	V <sub>EXTOFF</sub>	V <sub>BAT</sub> = 39.6V	-7.0		7.0	mV
		V <sub>BAT</sub> = 39.6V, -40 °C to +105 °C ( <u>Note 9</u> )	-10		10	mV
External Temperature Input INL	V <sub>EXTINL</sub>	(Note 9)		±0.61		mV
External Temperature Input Gain Error	V <sub>EXTG</sub>	Error at 2.5V input	-7.5		11	mV
		-40°C to +105°C (Note 9)	-8		18.5	mV



PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 7)	TYP	MAX (Note 7)	UNITS
V2P5 Power-good Window	V <sub>2PH</sub>	2.5V power-good window high threshold. V <sub>BAT</sub> = 39.6V	2.62	2.7	2.766	V
		-40°C to +105°C (Note 9)	2.616		2.77	V
	V <sub>2PL</sub> (Note 9)	2.5V power-good window low threshold. V <sub>BAT</sub> = 39.6V	1.96	2.02	2.08	V
		-40°C to +105°C	1.90		2.14	V

### To:

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 8)	ТҮР	MAX (Note 8)	UNIT
V2P5 Power-Good Window	V <sub>2PH</sub>	2.5V power-good window high threshold. V <sub>BAT</sub> = 39.6V	2.65	2.70	2.90	v
		-40°C to +105°C (Note 9)	2.53		2.90	V
	V <sub>2PL</sub>	2.5V power-good window low threshold. V <sub>BAT</sub> = 39.6V	1.85	2.03	2.24	V
	(Note 9)	-40°C to +105°C	1.76		2.28	V

#### From:

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 7)	TYP	MAX (Note 7)	UNITS
Open VC1 Detection Threshold	V <sub>VC1</sub>	CELL1 positive terminal (with respect to VSS) V <sub>BAT</sub> = 39.6V (Note 9)	0.6	0.7	0.8	V
Primary Detection Threshold, VC2 to VC12	V <sub>VC2_12P</sub>	V(VC(n - 1))-V(VCn), n = 2 to 12 V <sub>BAT</sub> = 39.6V ( <u>Note 9</u> )	-2	-1.5	0	v
Secondary Detection Threshold, VC2 to VC12	V <sub>VC2_12S</sub>	Via ADC. VC2 to VC12 only V <sub>BAT</sub> = 39.6V (Note 9)	-100	-30	50	mV

## To:

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 8)	TYP	MAX (Note 8)	UNIT
Open VC1 Detection Threshold	V <sub>VC1</sub>	CELL1 positive terminal (with respect to VSS) V <sub>BAT</sub> = 39.6V (Note 9)	0.6	0.7	0.8	V
Primary Detection Threshold, VC2 to VC12	V <sub>VC2_12P</sub>	V(VC(n - 1))-V(VCn), n = 2 to 12 V <sub>BAT</sub> = 39.6V ( <u>Note 9</u> )	<mark>-1.5</mark>	-1.2	-0.9	V
Secondary Detection Threshold, VC2 to VC12	V <sub>VC2_12S</sub>	Via ADC. VC2 to VC12 only V <sub>BAT</sub> = 39.6V ( <u>Note 9</u> )	-100	-39	10	mV

#### From:

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 7)	TYP	MAX (Note 7)	UNITS
MEASUREMENT FUNCTION TIMING (Note 8)						
Cell Sample Time Start		Time to sample the first cell (CELL12) following CS going High. Scan voltages command		65	71.5	μs
Cell Sample Time Duration		Time to scan all 12 cells (sample of CELL12 to sample of CELL1) scan voltages command.		233	257	μs
Scan Voltages Processing Time		Time from start of scan to registers loaded to DATA READY going low		770	847	μs
Scan Temperatures Processing Time		Time from start of scan to registers loaded to DATA READY going low		2690	2959	μѕ
Scan Mixed Processing Time		Time from start of scan to registers loaded to DATA READY going low		830	913	μs
Scan Wires Processing Time		Time from start of scan to registers loaded to DATA READY going low		59.4	65.3	ms
Scan All Processing Time		Time from start of scan to registers loaded to DATA READY going low		63.2	69.5	ms
Measure Cell Voltage Processing Time		Time from start of measurement to register(s) loaded to DATA READY going low		180	198	μs
Measure V <sub>BAT</sub> Voltage Processing Time		Time from start of measurement to register(s) loaded to DATA READY going low		130	143	μs
Measure Internal Temperature Processing Time		Time from start of measurement to register(s) loaded to DATA READY going low		110	121	μs
Measure External Temperature Input Processing Time		Time from start of measurement to register(s) loaded to DATA READY going low		2520	2772	μs
Measure Secondary Voltage Reference		Time from start of measurement to register(s) loaded to DATA READY going low		2520	2772	μs

8. Scan and Measurement start times are synchronised by the receiver to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 15<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 15<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 15<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or to the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or the falling edge of the 24<sup>th</sup> clock pulse (Dalsy Chain systems) or the falling edge

To: Removed from new datasheet



PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 7)	TYP	MAX (Note 7)	UNITS
DATA READY Start Delay Time	t <sub>DR:ST</sub>	Chip select high to DATA READY low. (Note 9)	100			ns
DATA READY Stop Delay Time	t <sub>DR:SP</sub>	Chip select high to DATA READY high. (Note 9)			750	ns
DATA READY High Time	t <sub>DR:WAIT</sub>	Time between bytes. (Note 9)	0.6			μs

## To:

# $t_{\text{DR:ST}}-$ removed from datasheet

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 8)	TYP	MAX (Note 8)	UNIT
DATA READY Stop Delay Time	t <sub>DR:SP</sub>	Chip select high to DATA READY high		750		ns
DATA READY High Time	t <sub>DR:WAIT</sub>	Time between bytes		1.0		μs